Product / Package Information

Package	CSP BGA
Body Size (mm)	6 X 6
Ball Count	96
Terminal Finish	SnAgCu
Ball Size (mm)	0.30

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.69 E-02	86.20	862000	27.44	274404
Thermosets	Epoxy resin	Proprietary	1.87 E-03	6.00	60000	1.91	19100
Thermosets	Phenol Resin	Proprietary	1.87 E-03	6.00	60000	1.91	19100
Other inorganic materials	Metal Hydroxide	Proprietary	4.68 E-04	1.50	15000	0.48	4775
Other inorganic materials	Carbon Black	1333-86-4	9.36 E-05	0.30	3000	0.10	955
Subtotal	Subtotal		3.12 E-02	100.0	1000000	31.83	318334

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper Foil	7440-50-8	8.95 E-03	20.76	207600	9.13	91314
Composite	Glass Cloth	65997-17-3	1.08 E-02	25.04	250400	11.01	110140
Thermoset	Epoxy resin	7238-97-4	2.16 E-03	5.01	50100	2.20	22037
Thermoset	Bismaleimide	13676-54-5	2.16 E-03	5.01	50100	2.20	22037
Thermoset	Triazine	25722-66-1	2.16 E-03	5.01	50100	2.20	22037
Other inorganic materials	Inorganic filler	Proprietary	4.32 E-03	10.02	100200	4.41	44074
	Laminate Core Subtotal		3.06 E-02	70.85	708500	31.16	311638
Other organic materials	Modified resin	Proprietary	1.52 E-03	3.52	35200	1.55	15483
Other inorganic materials	Barium Sulfate	7727-43-7	1.55 E-03	3.59	35900	1.58	15791
Other organic materials	Aromatic hydrocarbon	Proprietary	8.54 E-04	1.98	19800	0.87	8709
Other organic materials	Diethylene Glycol Monomethyl Ether Acetate	112-15-2	5.48 E-04	1.27	12700	0.56	5586
Thermoset	Epoxy resin	85954-11-6	7.98 E-04	1.85	18500	0.81	8137
Other organic materials	Acrylic ester monomer	Proprietary	2.33 E-04	0.54	5400	0.24	2375
Other organic materials	Aromatic Carbonyl Compound	Proprietary	1.51 E-04	0.35	3500	0.15	1539
Other inorganic materials	Dipropylene gylcol monomethyl ether	34590-94-8	1.42 E-04	0.33	3300	0.15	1452
Other inorganic materials	Levelling Agents & Others	Proprietary	9.49 E-05	0.22	2200	0.10	968
Other organic materials	Organic Filler	Proprietary	7.76 E-05	0.18	1800	0.08	792
Other organic materials	Amine Compound	Proprietary	2.59 E-05	0.06	600	0.03	264
Other organic materials	Phthalocyanine Green	Proprietary	1.29 E-05	0.03	300	0.01	132
	Soldermask Subtotal		6.00 E-03	13.92	139200	6.12	61228
Copper & its alloys	Copper	7440-50-8	5.23 E-03	12.12	121200	5.33	53311
Nickel & its alloys	Nickel	7440-02-0	1.20 E-03	2.78	27800	1.22	12228
Precious metals	Gold	7440-57-5	1.42 E-04	0.33	3300	0.15	1452
Subtotal			4.31 E-02	100.00	1000000	43.99	439857

Solder Ball

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.69 E-03	96.50	965000	9.88	98838
Tin & its alloys	Silver	7440-22-4	3.01 E-04	3.00	30000	0.31	3073
Tin & its alloys	Copper	7440-50-8	5.02 E-05	0.50	5000	0.05	512
Subtotal			1.00 E-02	100	1000000	10.24	102423

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.28 E-04	99	990000	0.84	8448
Precious metals	Palladium	7440-05-3	8.37 E-06	1	10000	0.009	85
Subtotal			8.37 E-04	100	1000000	0.85	8534

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.19 E-02	100	1000000	12.14	121447

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Acrylic copolymer	Proprietary	6.12 E-04	66.35	663500	0.62	6241
Other organic materials	Epoxy Resin	Proprietary	1.31 E-04	14.22	142200	0.13	1337
Other organic materials	Phenol Resin	Proprietary	1.31 E-04	14.22	142200	0.13	1337
Other inorganic materials	Silicon Dioxide	Proprietary	4.80 E-05	5.21	52100	0.05	490
Subtotal			9.22 E-04	100.00	1000000	0.94	9405

	Weight (g)	Percentage (%)	PPM
Package Totals	**9.81 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES